

Description

The STP607D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = -60V I_D =-10 A

 $R_{DS(ON)} < 140 m\Omega @ V_{GS}=10V$

Application

Brushless motor

Load switch

Uninterruptible power supply

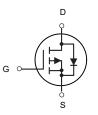
Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
STP607D	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Parameter Rating	
Vds	Drain-Source Voltage	-60	V
Vgs	Gate-Source Voltage	±20	V
l₀@Tc=25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-10	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-8.3	A
Ірм	Pulsed Drain Current ²	-26	А
EAS	Single Pulse Avalanche Energy ³	ngle Pulse Avalanche Energy ³ 29.8	
las	Avalanche Current	-24.4	А
P _D @T _C =25°C	Total Power Dissipation ⁴	31.3	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-Ambient ¹	62 °C/W	
Rejc	Thermal Resistance Junction-Case ¹	4.0 °C/W	





P-Channel MOSFET



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V	
$\triangle BV_{DSS} / \triangle T$	BV _{DSS} Temperature Coefficient	Reference to $25^{\circ}C$, I _D =-1mA		-0.049		V/°C	
5	Statia Drain Source On Desistance ²	V _{GS} =-10V , I _D =-8A	125 140				
R _{DS(ON)}	Static Drain-Source On-Resistance ² $V_{GS} = -4.5V$, $I_D = -6A$		168	210	mΩ		
$V_{\text{GS(th)}}$	Gate Threshold Voltage		-1.0		-2.5	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	—V _{GS} =V _{DS} , I _D =-250uA		5.42		mV/°C	
	V _{DS} =-48V , V _{GS} =0V , T _J =25°C	V _{DS} =-48V , V _{GS} =0V , T _J =25°C			1		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-48V , V _{GS} =0V , T _J =150°C			5	uA	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-5A		5.8		S	
Qg	Total Gate Charge (-4.5V)			5.85			
Q_gs	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-4.5V , I _D =-5A		2.9		nC	
Q_{gd}	Gate-Drain Charge			1.8			
T _{d(on)}	Turn-On Delay Time			10			
Tr	Rise Time	V_{DD} =-12V , V_{GS} =-10V , R_{G} =3.3 Ω ,		17		- ns	
T _{d(off)}	Turn-Off Delay Time	I _D =-5A		22			
T _f	Fall Time			21			
Ciss	Input Capacitance			715			
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , F=1MHz		51		pF	
C _{rss}	Reverse Transfer Capacitance			34			
ls	Continuous Source Current ^{1,5}				-9.5	А	
I _{SM}	Pulsed Source Current ^{2,5}	──V _G =V _D =0V , Force Current			-24	А	
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I _S =-1A , T _J =25 $^{\circ}$ C			-1.2	V	
t _{rr}	Reverse Recovery Time			10.2		nS	
Qrr	Reverse Recovery Charge	I⊧=-8A , dl/dt=100A/μs , Tյ=25°C		5.4		nC	

Note :

1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.

2. The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating. The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH,I_{AS}=-15A

4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

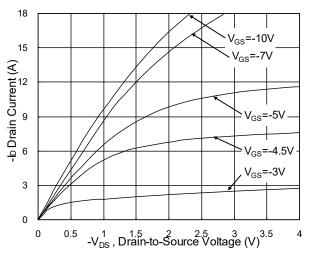


Fig.1 Typical Output Characteristics

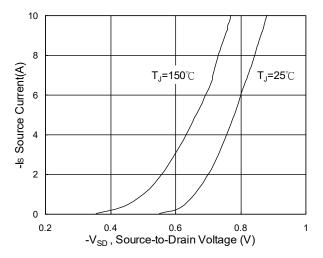
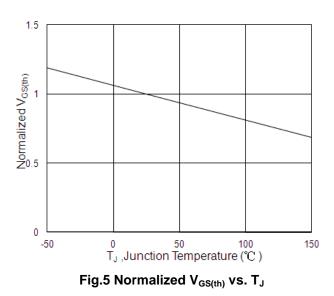


Fig.3 Forward Characteristics Of Reverse



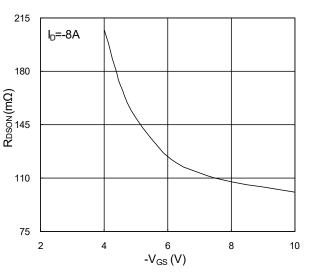


Fig.2 On-Resistance vs. G-S Voltage

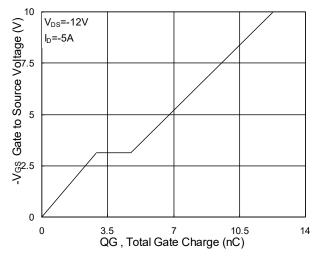


Fig.4 Gate-Charge Characteristics

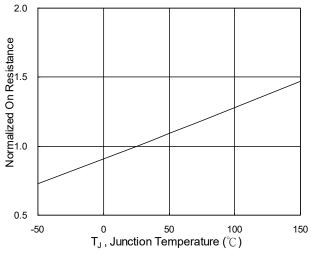
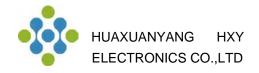
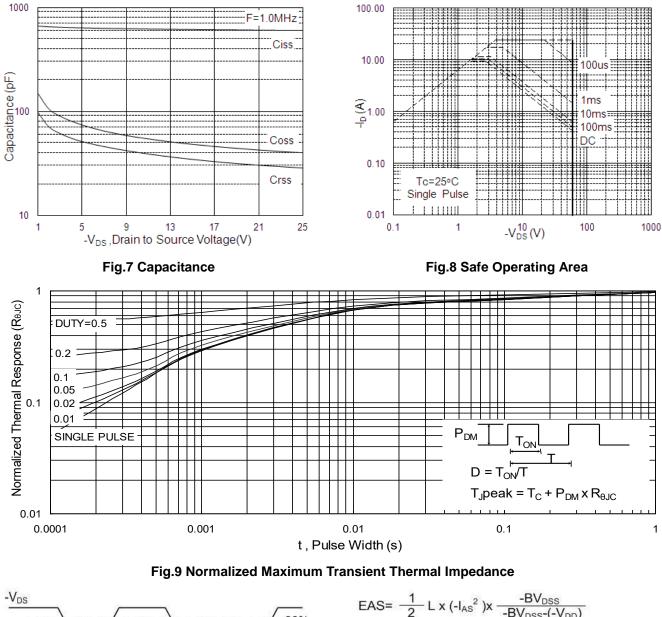


Fig.6 Normalized R_{DSON} vs. T_J





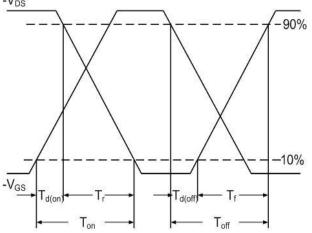


Fig.10 Switching Time Waveform

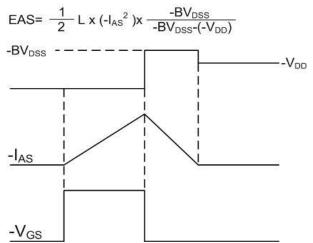
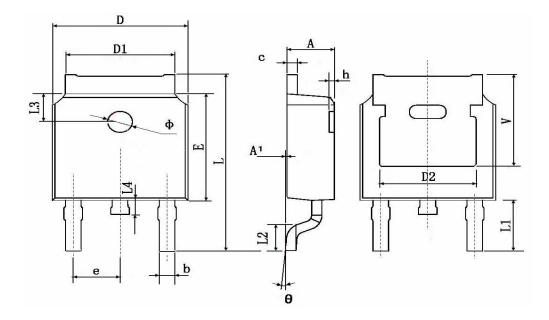


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
с	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3		1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0 °	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211	0.211 TYP.	



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